

In the Claims:

Please enter the following claims as amended:

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2. The power processing device according to claim 1, further including a first shielding layer on a first exterior surface of said multilayer printed circuit board, said first shielding layer being disposed between a first winding of said first set of windings and a winding of said second set of windings.

3. The power processing device according to claim 2, further including a second shielding layer disposed on a second exterior surface of said multilayer printed circuit board, said second shielding layer being disposed between a second winding of said first set of windings and said winding of said second set of windings.

7. The power processing device according to claim 1,

a) wherein said first transformer further includes a secondary set of windings positioned to have electrical flow induced therein by said first core; and

b) further including an open loop of electrically conductive material positioned to inject a current through parasitic capacitance in said secondary windings having a polarity opposite that of current in said first set of windings.

8. The power processing device according to claim 1,

- a) wherein said first transformer further includes a secondary set of windings positioned to have electrical flow induced therein by said first core; and
- b) further including an open loop of electrically conductive material positioned proximate and on a second side of said secondary windings.

10. A power processing device comprising:

- a) a multilayer printed circuit board having multiple layers of dielectric sheets;
- b) a transformer having,
  - 1) a core extending through said layers of dielectric sheets; and
  - 2) a first set of electrically conductive windings, at least one of said windings of said first set of electrically conductive windings contained between two adjoining layers of said dielectric sheets; and

- c) a first shielding layer disposed on a first exterior surface of said multilayer printed circuit board, said first shielding layer being disposed adjacent to and on one side of a winding of said first set of windings.

11. The power processing device according to claim 10, further including a second shielding layer disposed on a second exterior surface of said multilayer printed circuit board, said second shielding layer being disposed adjacent to and on the other side of said winding of said first set of windings.

14. The power processing device according to claim 10, further including:

- a) a secondary set of windings positioned to have electrical flow induced therein by said core; and
- b) an open loop of electrically conductive material positioned to inject a current through parasitic capacitance in said secondary windings, said injected current having a polarity opposite that of current in said first set of windings.

15. The power processing device according to claim 10, further including:


- a) a secondary set of windings positioned to have electrical flow induced therein by said core; and
- b) further including an open loop of electrically conductive material

positioned proximate and on a second side of said secondary windings.

In the Claims:

Amend claims 2, 3, 7, 8, 10, 11, 14 and 15 as follows:

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 --2 (twice amended). The power processing device according to claim 1, further including a first shielding [winding] layer on a first exterior surface [layer] of said multilayer printed circuit board, said first shielding [winding] layer being disposed between a first winding of said first set of windings and a winding of said second set of windings.


3 (twice amended). The power processing device according to claim 2, further including a second shielding [winding] layer disposed on a second exterior surface [layer] of said multilayer printed circuit board, said second shielding [winding] layer being disposed between a second winding of said first set of windings and said winding of said second set of windings.

10 (twice amended). A power processing device comprising:

- a) a multilayer printed circuit board having multiple layers of dielectric sheets;
- b) a transformer having,
  - 1) a core extending through said layers of dielectric sheets; and
  - 2) a first set of electrically conductive windings, at least one of said windings of said first set of electrically conductive windings contained between two adjoining

layers of said dielectric sheets; and[,]

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- c) a first shielding [winding] layer disposed on a first [layer] exterior surface of said multilayer printed circuit board, said first shielding [winding] layer being disposed adjacent to and on one side of a winding of said first set of windings.
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11 (amended). The power processing device according to claim 10, further including a second shielding [winding] layer disposed on a second [layer] exterior surface of said multilayer printed circuit board, said second shielding [winding] layer being disposed adjacent to and on the other side of said winding of said first set of windings.--

In claim 7, line 5, change "open loop" to --open loop of electrically conductive material--.

In claim 8, line 5, change "open loop" to --open loop of electrically conductive material--.

In claim 14, line 5, change "open loop" to --open loop of electrically conductive material--.

In claim 15, line 5, change "open loop" to --open loop of electrically conductive material--.

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